

Analog Multiplexers/ Demultiplexers with Injection Current Effect Control with LSTTL Compatible Inputs

Automotive Customized



ON Semiconductor®

www.onsemi.com

MC74HCT4851A, MC74HCT4852A

This device is pin compatible to standard HC405x and MC1405xB analog mux/demux devices, but feature injection current effect control. This makes them especially suited for usage in automotive applications where voltages in excess of normal logic voltage are common.

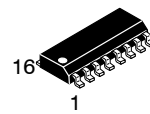
The injection current effect control allows signals at disabled analog input channels to exceed the supply voltage range without affecting the signal of the enabled analog channel. This eliminates the need for external diode/ resistor networks typically used to keep the analog channel signals within the supply voltage range.

The devices utilize low power silicon gate CMOS technology. The Channel Select and Enable inputs are compatible with standard CMOS or LSTTL outputs.

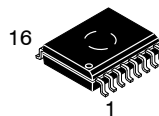
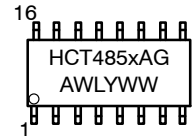
Features

- Injection Current Cross-Coupling Less than 1mV/mA (See Figure 6)
- Pin Compatible to HC405x and MC1405xB Devices
- Power Supply Range ($V_{CC} - GND$) = 4.5 to 5.5 V
- In Compliance With the Requirements of JEDEC Standard No. 7 A
- Chip Complexity: 154 FETs or 36 Equivalent Gates
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

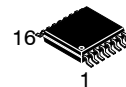
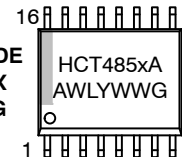
MARKING DIAGRAMS



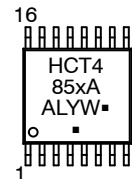
SOIC-16
D SUFFIX
CASE 751B



SOIC-16 WIDE
DW SUFFIX
CASE 751G



TSSOP-16
DT SUFFIX
CASE 948F



X = 1 or 2
A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information on page 11 of this data sheet.

MC74HCT4851A, MC74HCT4852A

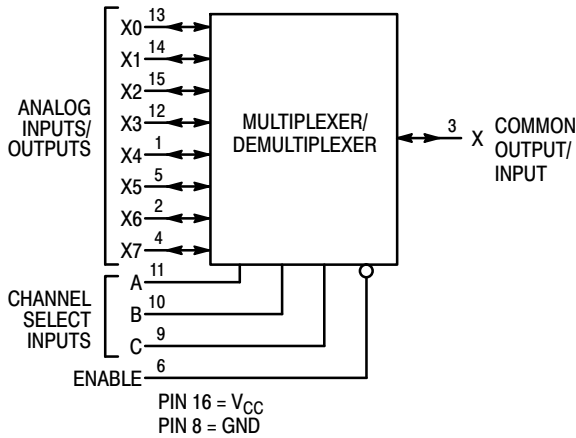


Figure 1. MC74HCT4851A Logic Diagram Single-Pole, 8-Position Plus Common Off

FUNCTION TABLE - MC74HCT4851A

Control Inputs					ON Channels
Enable	Select				
	C	B	A		
L	L	L	L	X0	
L	L	L	H	X1	
L	L	H	L	X2	
L	L	H	H	X3	
L	H	L	L	X4	
L	H	L	H	X5	
L	H	H	L	X6	
L	H	H	H	X7	
H	X	X	X	NONE	

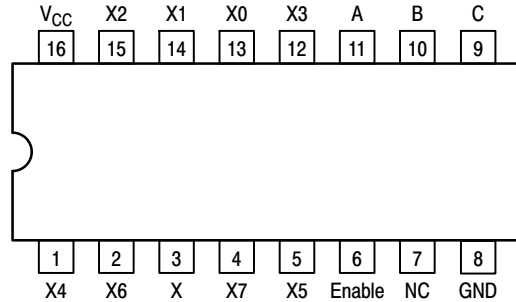


Figure 2. MC74HCT4851A 16-Lead Pinout (Top View)

FUNCTION TABLE - MC74HCT4852A

Control Inputs				ON Channels	
Enable	Select				
	B	A			
L	L	L	Y0	X0	
L	L	H	Y1	X1	
L	H	L	Y2	X2	
L	H	H	Y3	X3	
H	X	X	NONE		

X = Don't Care

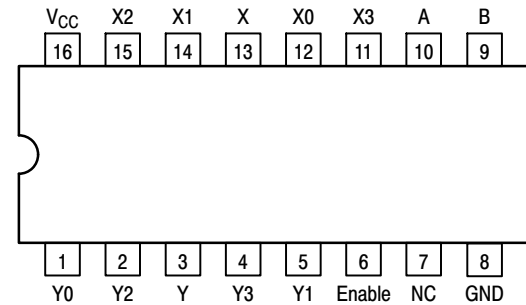


Figure 4. MC74HCT4852A 16-Lead Pinout (Top View)

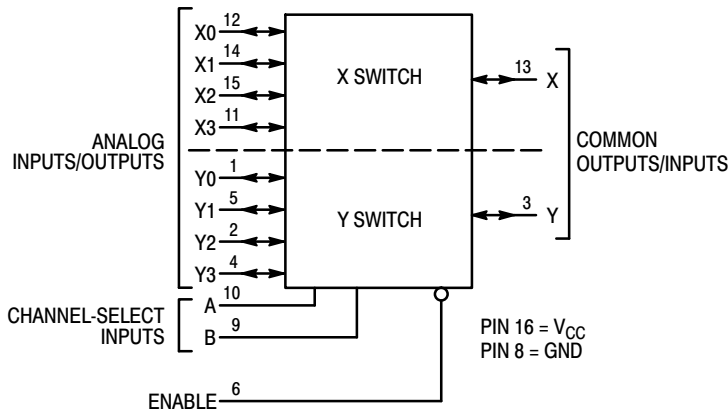


Figure 3. MC74HCT4852A Logic Diagram Double-Pole, 4-Position Plus Common Off

MC74HCT4851A, MC74HCT4852A

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{CC}	Positive DC Supply Voltage (Referenced to GND)	-0.5 to + 7.0	V
V_{in}	DC Input Voltage (Any Pin) (Referenced to GND)	-0.5 to $V_{CC} + 0.5$	V
I	DC Current, Into or Out of Any Pin	± 25	mA
P_D	Power Dissipation in Still Air, SOIC Package† TSSOP Package†	500 450	mW
T_{stg}	Storage Temperature Range	-65 to + 150	°C
T_L	Lead Temperature, 1 mm from Case for 10 Seconds SOIC or TSSOP Package	260	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $GND \leq (V_{in} \text{ or } V_{out}) \leq V_{CC}$. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit	
V_{CC}	Positive DC Supply Voltage (Referenced to GND)	4.5	5.5	V	
V_{in}	DC Input Voltage (Any Pin) (Referenced to GND)	GND	V_{CC}	V	
V_{IO}^*	Static or Dynamic Voltage Across Switch	0.0	1.2	V	
T_A	Operating Temperature Range, All Package Types	-55	+ 125	°C	
t_r, t_f	Input Rise/Fall Time (Channel Select or Enable Inputs)	$V_{CC} = 2.0 \text{ V}$ $V_{CC} = 4.5 \text{ V}$ $V_{CC} = 6.0 \text{ V}$	0 0 0	1000 500 400	ns

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

*For voltage drops across switch greater than 1.2 V (switch on), excessive V_{CC} current may be drawn; i.e., the current out of the switch may contain both V_{CC} and switch input components. The reliability of the device will be unaffected unless the Maximum Ratings are exceeded.

DC CHARACTERISTICS — Digital Section (Voltages Referenced to GND) $V_{EE} = GND$, Except Where Noted

Symbol	Parameter	Condition	V_{CC} V	Guaranteed Limit			Unit
				-55 to 25°C	≤85°C	≤125°C	
V_{IH}	Minimum High-Level Input Voltage, Channel-Select or Enable Inputs	$R_{on} = \text{Per Spec}$	4.5 to 5.5	2.0	2.0	2.0	V
V_{IL}	Maximum Low-Level Input Voltage, Channel-Select or Enable Inputs	$R_{on} = \text{Per Spec}$	4.5 to 5.5	0.8	0.8	0.8	V
I_{in}	Maximum Input Leakage Current on Digital Pins (Enable/A/B/C)	$V_{in} = V_{CC} \text{ or } GND$	5.5	± 0.1	± 1.0	± 1.0	μA
I_{CC}	Maximum Quiescent Supply Current (per Package)	$V_{in(digital)} = V_{CC} \text{ or } GND$ $V_{in(analog)} = GND$	5.5	2.0	20	40	μA

MC74HCT4851A, MC74HCT4852A

DC CHARACTERISTICS — Analog Section

Symbol	Parameter	Condition	V _{CC}	Guaranteed Limit			Unit
				-55 to 25°C	≤85°C	≤125°C	
R _{on}	Maximum "ON" Resistance	V _{in} = V _{IL} or V _{IH} ; V _{IS} = V _{CC} to GND (Note 1); I _S ≤ 2.0 mA (Note 2)	4.5 5.5	550 400	650 500	750 600	Ω
ΔR _{on}	Delta "ON" Resistance	V _{in} = V _{IL} or V _{IH} ; V _{IS} = V _{CC} /2 (Note 1); I _S ≤ 2.0 mA (Note 2)	4.5 5.5	80 60	100 80	120 100	Ω
I _{off}	Maximum Off-Channel Leakage Current, Any One Channel Common Channel	V _{in} = V _{CC} or GND	5.5	±0.1 ±0.1	±0.1 ±0.1	±0.1 ±0.1	μA
I _{on}	Maximum On-Channel Leakage Channel-to-Channel	V _{in} = V _{CC} or GND	5.5	±0.1	±0.1	±0.1	μA

1. V_{IS} is the input voltage of an analog I/O pin.
2. I_S is the current flowing in or out of analog I/O pin.

AC CHARACTERISTICS (C_L = 50 pF, Input t_r = t_f = 6 ns, V_{CC} = 5.0 V ± 10%)

Symbol	Parameter	V _{CC}	-55 to 25°C	≤85°C	≤125°C	Unit
t _{PHL} , t _{PLH}	Maximum Propagation Delay, Analog Input to Analog Output	5.0	40	45	50	ns
t _{PHL} , t _{PHZ,PZH} , t _{PLH} , t _{PLZ,PZL}	Maximum Propagation Delay, Enable or Channel-Select to Analog Output	5.0	80	90	100	ns
C _{in}	Maximum Input Capacitance (All Switches Off)	Digital Pins Any Single Analog Pin Common Analog Pin	10 35 40	10 35 40	10 35 40	pF
C _{PD}	Power Dissipation Capacitance	Typical	20			pF

INJECTION CURRENT COUPLING SPECIFICATIONS (V_{CC} = 5V, T_A = -55°C to +125°C)

Symbol	Parameter	Condition	Typ	Max	Unit
VΔ _{out}	Maximum Shift of Output Voltage of Enabled Analog Channel	I _{in} * ≤ 1 mA, R _S ≤ 3,9 kΩ I _{in} * ≤ 10 mA, R _S ≤ 3,9 kΩ I _{in} * ≤ 1 mA, R _S ≤ 20 kΩ I _{in} * ≤ 10 mA, R _S ≤ 20 kΩ	0.1 1.0 0.5 5.0	1.0 5.0 2.0 20	mV

* I_{in} = Total current injected into all disabled channels.

MC74HCT4851A, MC74HCT4852A

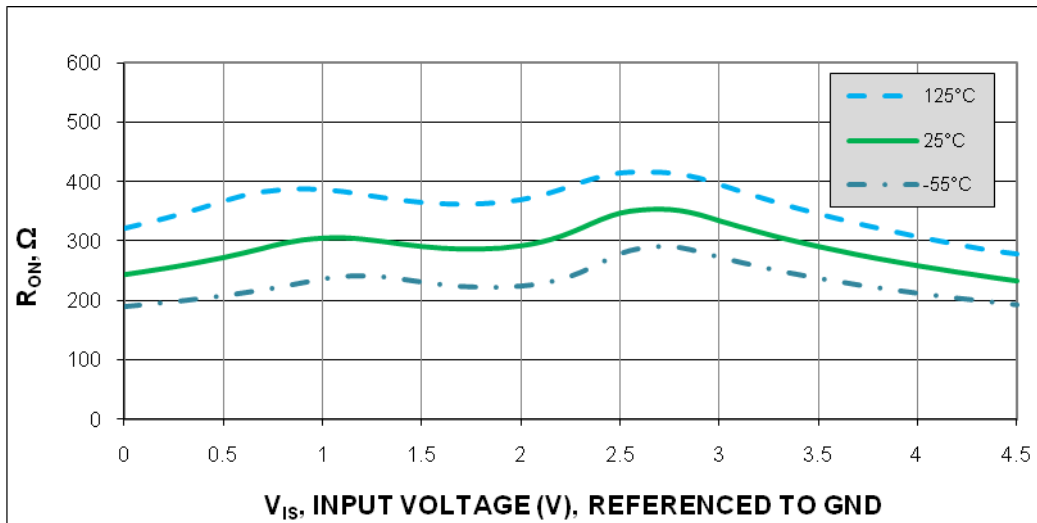


Figure 5. Typical On Resistance $V_{CC} = 4.5V$

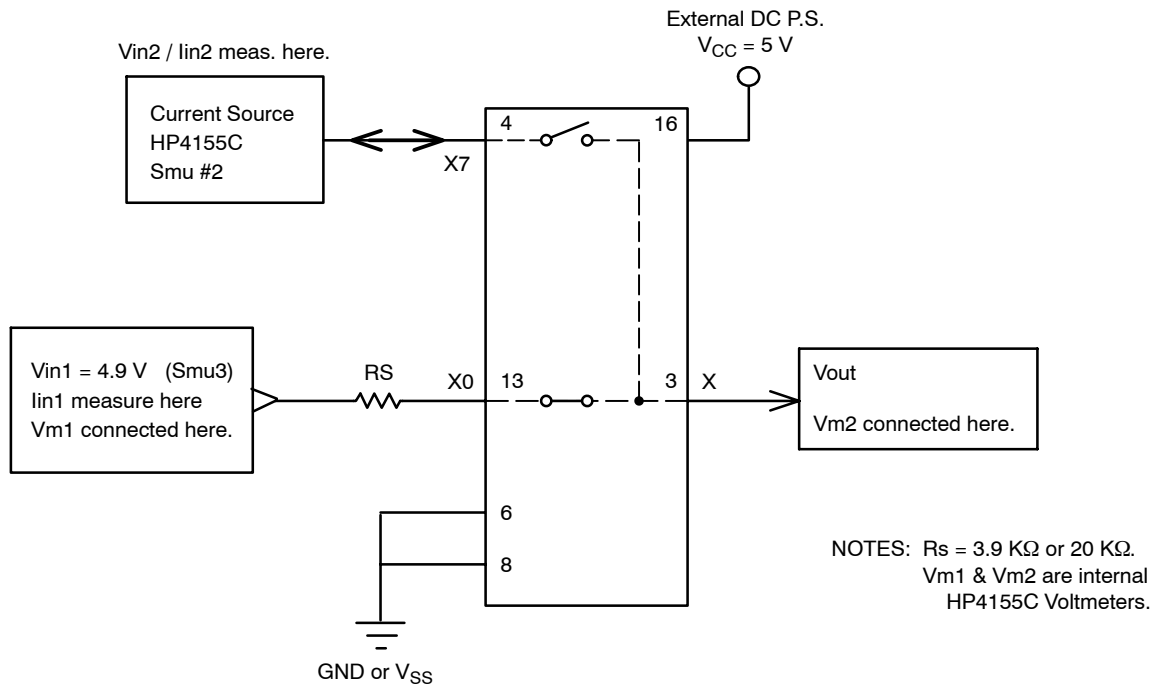


Figure 6. Injection Current Coupling Specification

MC74HCT4851A, MC74HCT4852A

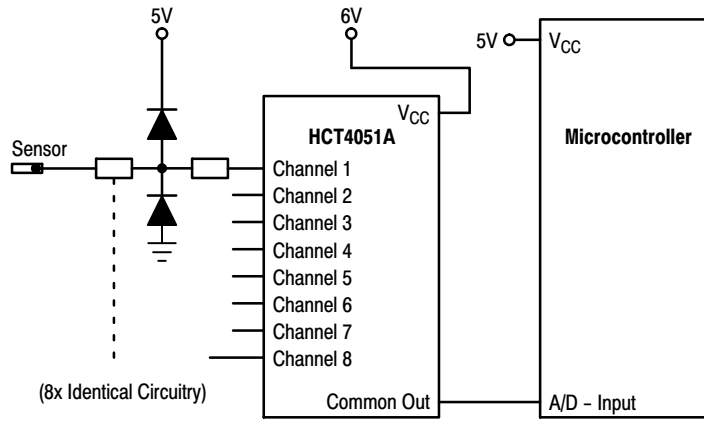


Figure 7. Actual Technology

Requires 32 passive components and one extra 6V regulator to suppress injection current into a standard HCT4051 multiplexer

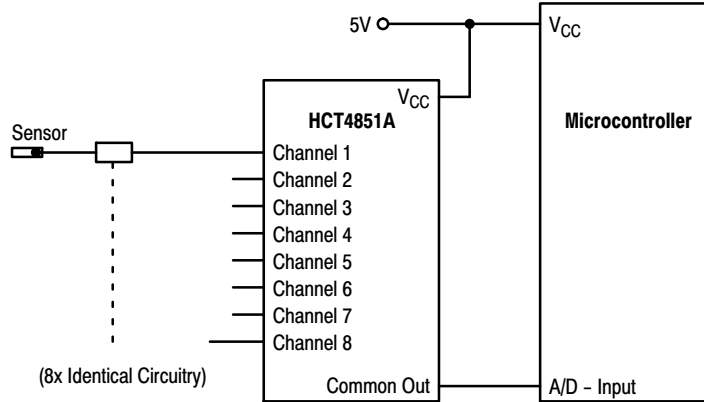


Figure 8. MC74HCT4851A Solution

Solution by applying the HCT4851A multiplexer

MC74HCT4851A, MC74HCT4852A

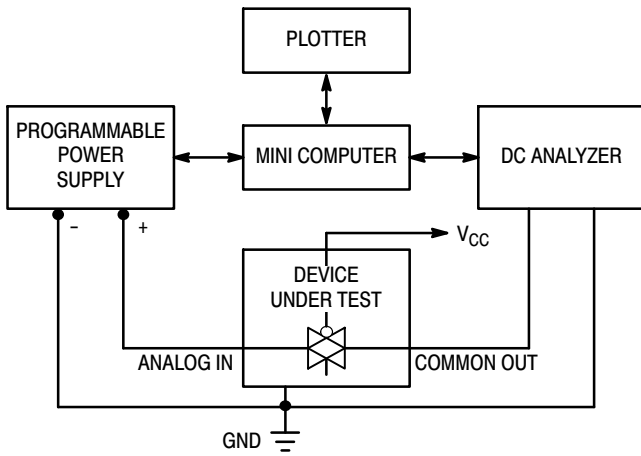


Figure 9. On Resistance Test Set-Up

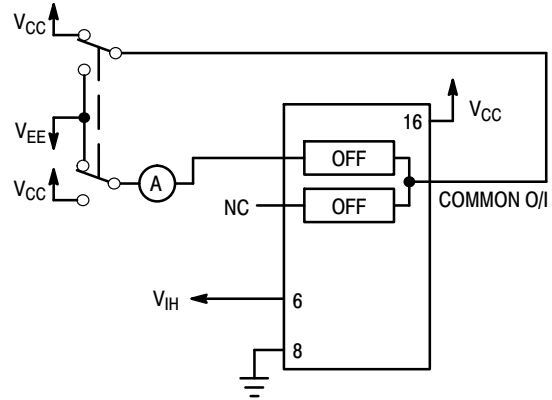


Figure 10. Maximum Off Channel Leakage Current, Any One Channel, Test Set-Up

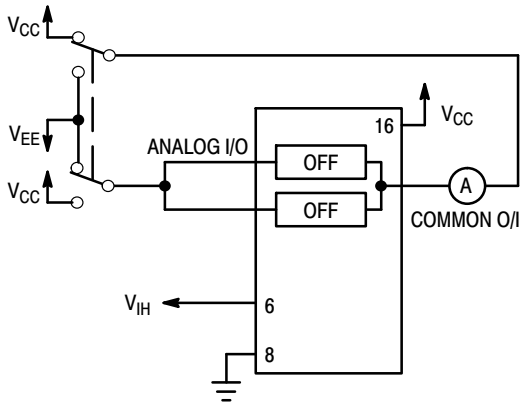


Figure 11. Maximum Off Channel Leakage Current, Common Channel, Test Set-Up

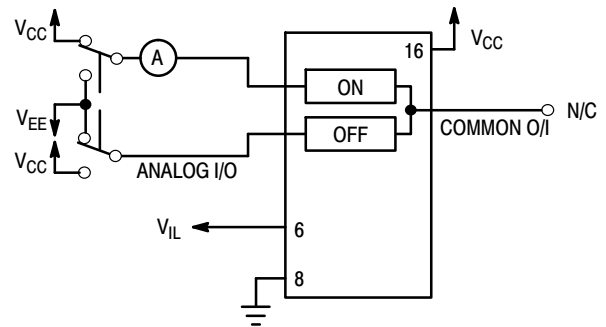


Figure 12. Maximum On Channel Leakage Current, Channel to Channel, Test Set-Up

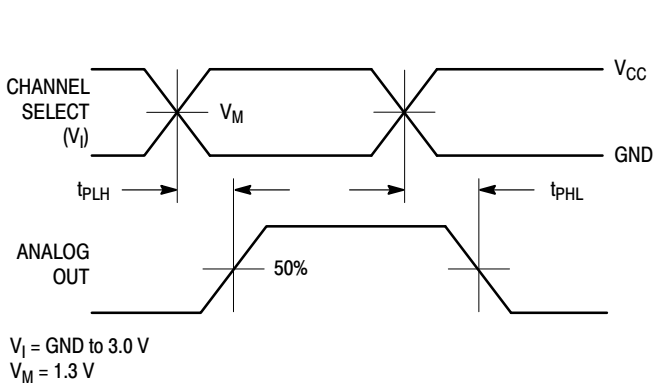
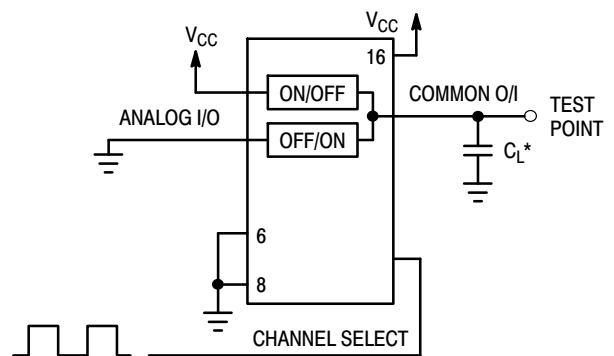


Figure 13. Propagation Delays, Channel Select to Analog Out



*Includes all probe and jig capacitance

Figure 14. Propagation Delay, Test Set-Up Channel Select to Analog Out

MC74HCT4851A, MC74HCT4852A

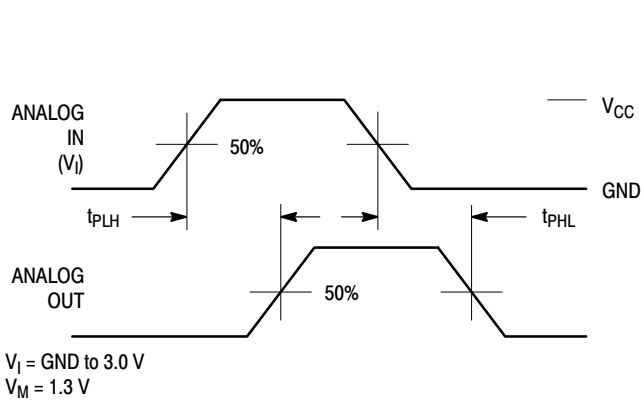
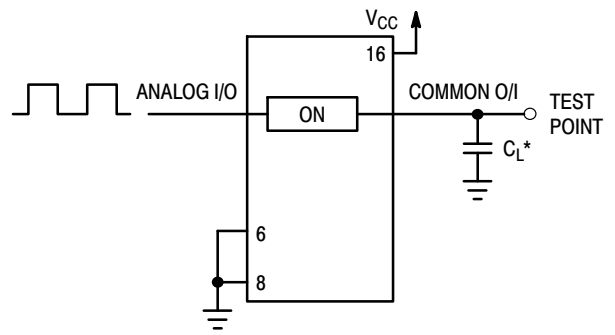


Figure 15. Propagation Delays, Analog In to Analog Out



*Includes all probe and jig capacitance

Figure 16. Propagation Delay, Test Set-Up Analog In to Analog Out

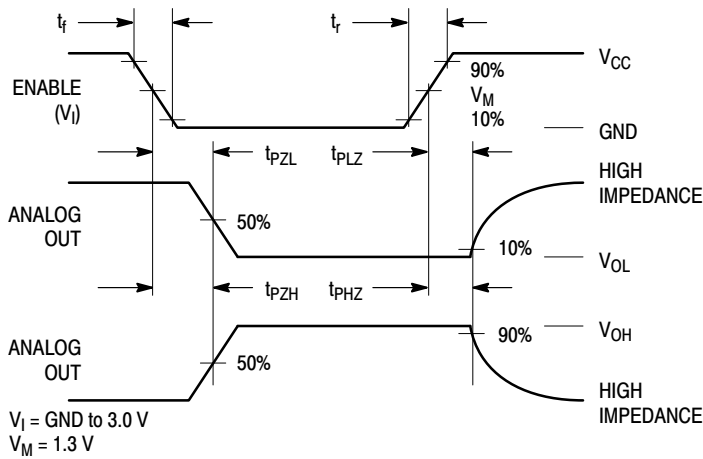


Figure 17. Propagation Delays, Enable to Analog Out

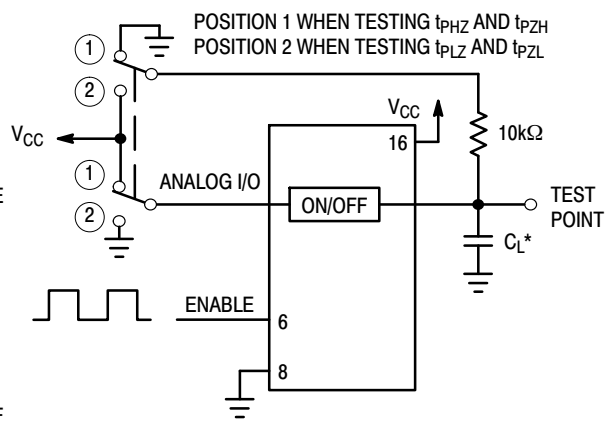


Figure 18. Propagation Delay, Test Set-Up Enable to Analog Out

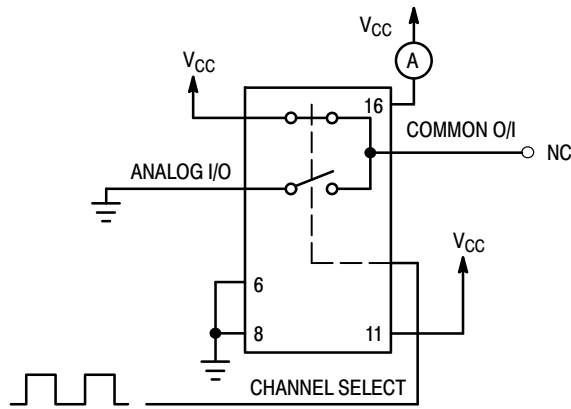


Figure 19. Power Dissipation Capacitance, Test Set-Up

MC74HCT4851A, MC74HCT4852A

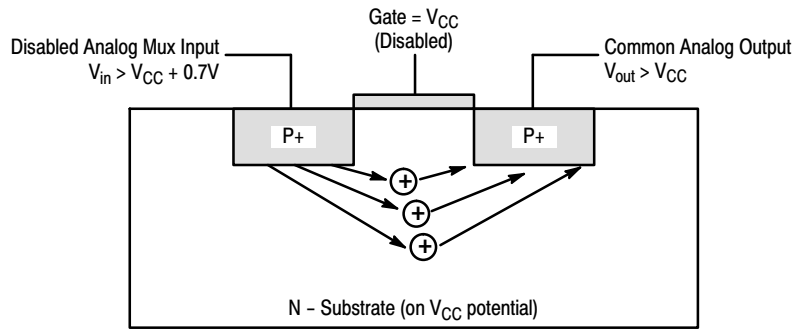


Figure 20. Diagram of Bipolar Coupling Mechanism
Appears if V_{in} exceeds V_{CC}, driving injection current into the substrate

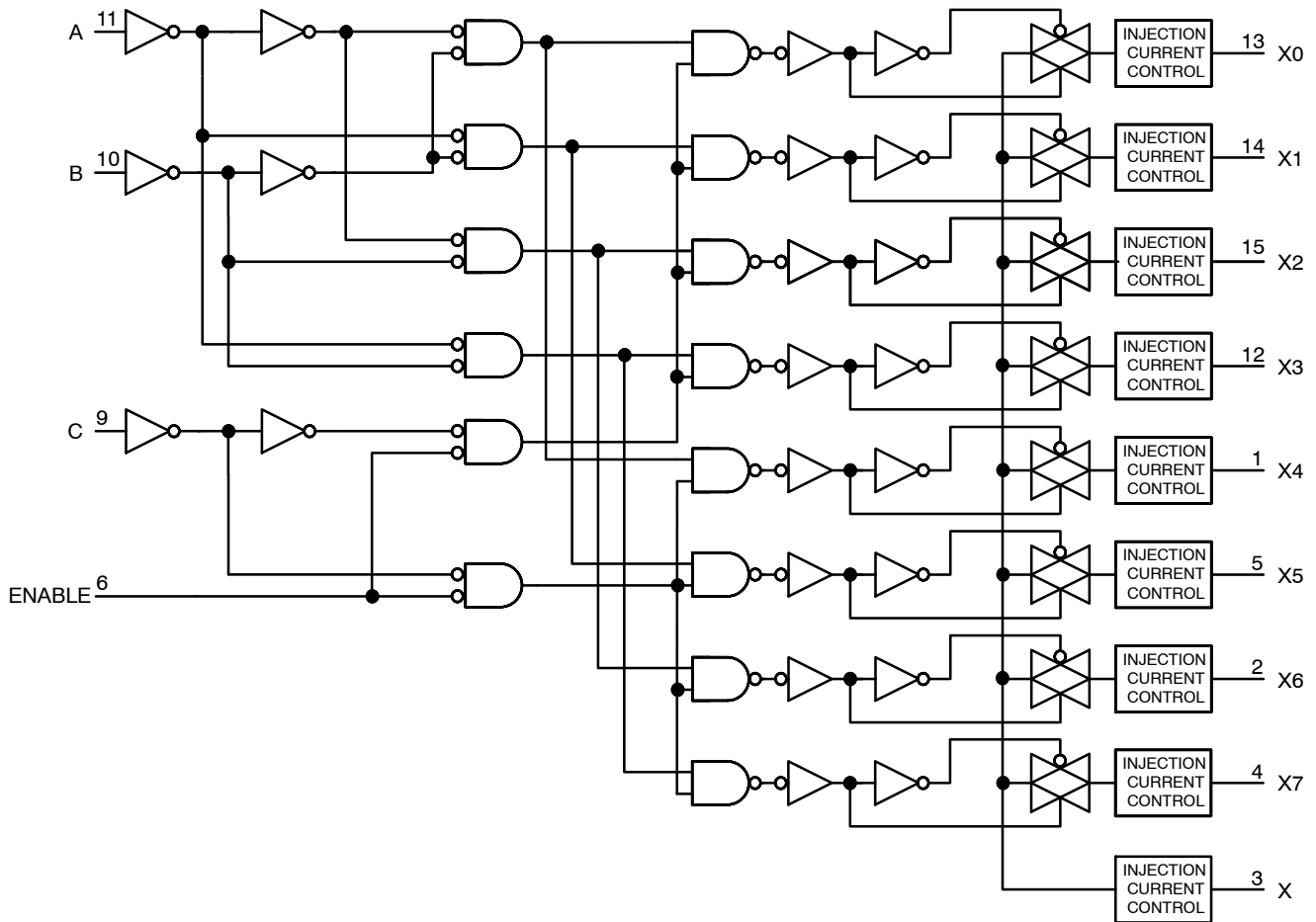


Figure 21. Function Diagram, HCT4851A

MC74HCT4851A, MC74HCT4852A

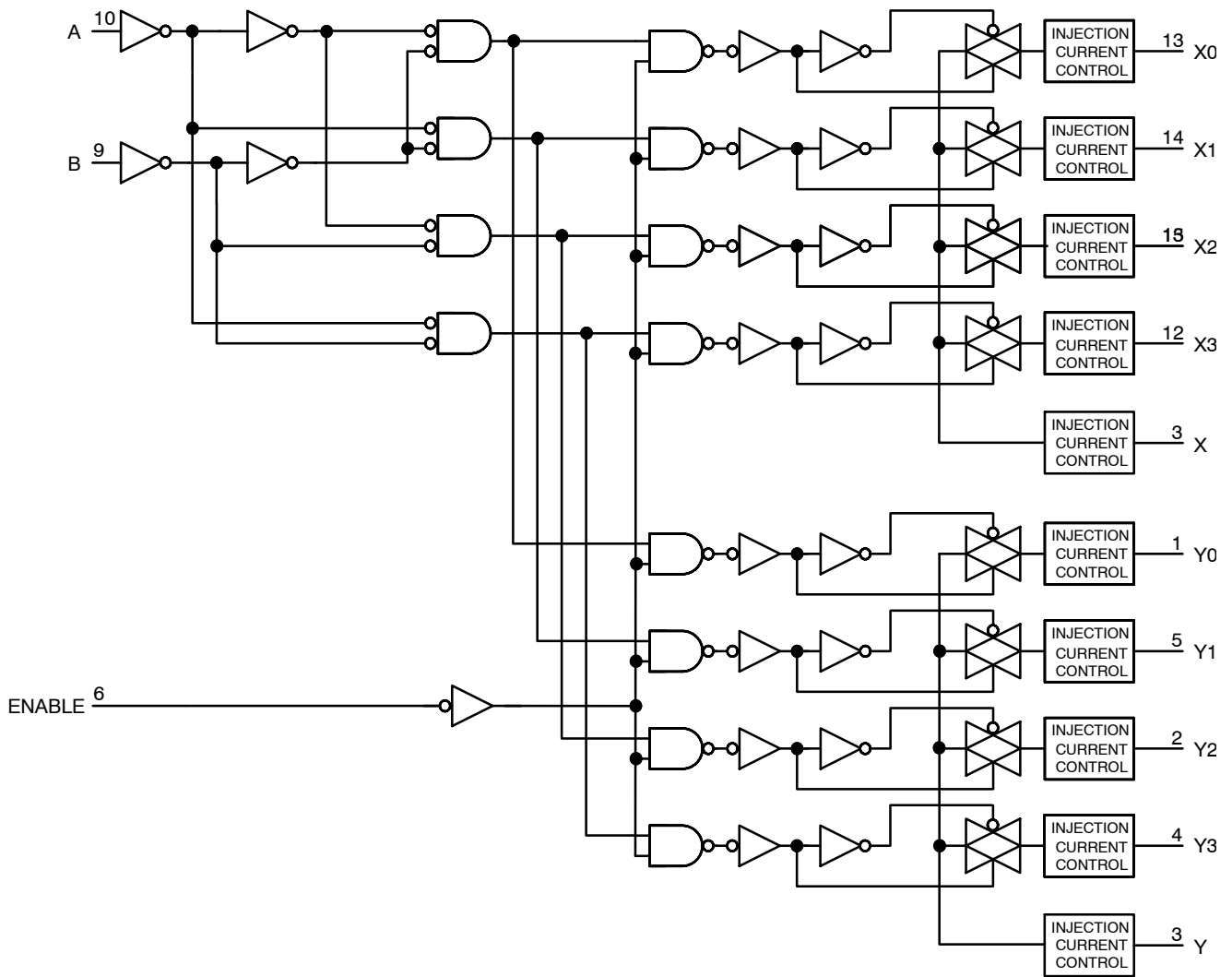


Figure 22. Function Diagram, HCT4852A

MC74HCT4851A, MC74HCT4852A

ORDERING INFORMATION

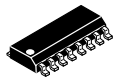
Device	Package	Shipping†
MC74HCT4851ADG	SOIC-16 (Pb-Free)	48 Units / Rail
MC74HCT4851ADR2G		2500 Units / Tape & Reel
NLV74HCT4851ADRG*		2500 Units / Tape & Reel
MC74HCT4851AADR2G		2500 Units / Tape & Reel
NLV74HCT4851AADR2G* (Contact ON Semiconductor)		2500 Units / Tape & Reel
MC74HCT4851ADTG	TSSOP-16 (Pb-Free)	48 Units / Rail
M74HCT4851ADTR2G		2500 Units / Tape & Reel
NLVHCT4851ADTR2G*		2500 Units / Tape & Reel
M74HCT4851ADWR2G	SOIC-16 WIDE (Pb-Free)	1000 Units / Tape & Reel
MC74HCT4852ADG	SOIC-16 (Pb-Free)	48 Units / Rail
MC74HCT4852ADR2G		2500 Units / Tape & Reel
MC74HCT4852ADTG	TSSOP-16 (Pb-Free)	48 Units / Rail
M74HCT4852ADTR2G		2500 Units / Tape & Reel
NLVHCT4852ADTR2G*		2500 Units / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

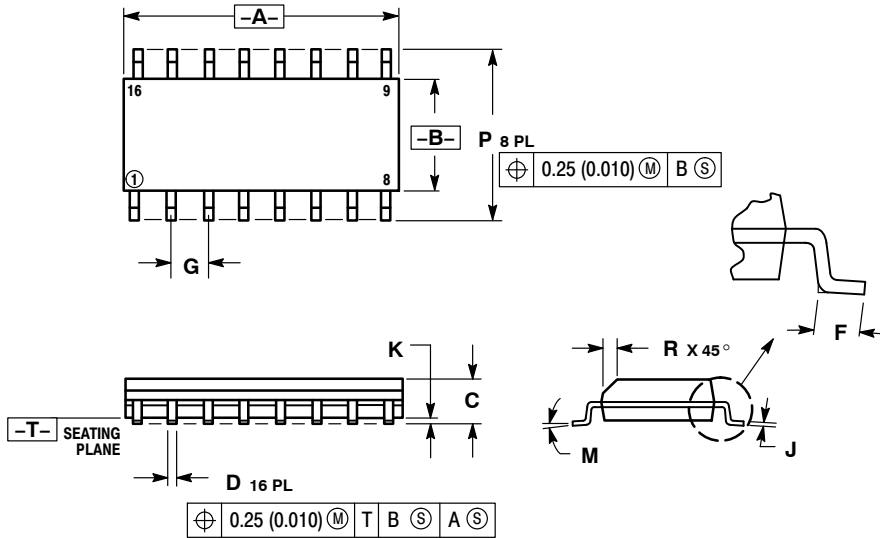
ON Semiconductor®



SCALE 1:1

SOIC-16 CASE 751B-05 ISSUE K

DATE 29 DEC 2006



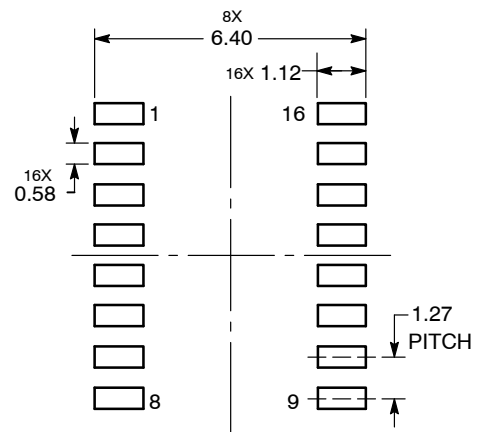
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

- | | | | |
|---|---|---|---|
| <p>STYLE 1:</p> <p>PIN 1. COLLECTOR
2. BASE
3. EMITTER
4. NO CONNECTION
5. EMITTER
6. BASE
7. COLLECTOR
8. COLLECTOR
9. BASE
10. EMITTER
11. NO CONNECTION
12. EMITTER
13. BASE
14. COLLECTOR
15. EMITTER
16. COLLECTOR</p> | <p>STYLE 2:</p> <p>PIN 1. CATHODE
2. ANODE
3. NO CONNECTION
4. CATHODE
5. CATHODE
6. NO CONNECTION
7. ANODE
8. CATHODE
9. CATHODE
10. ANODE
11. NO CONNECTION
12. CATHODE
13. CATHODE
14. NO CONNECTION
15. ANODE
16. CATHODE</p> | <p>STYLE 3:</p> <p>PIN 1. COLLECTOR, DYE #1
2. BASE, #1
3. EMITTER, #1
4. COLLECTOR, #1
5. COLLECTOR, #2
6. BASE, #2
7. EMITTER, #2
8. COLLECTOR, #2
9. COLLECTOR, #3
10. BASE, #3
11. EMITTER, #3
12. COLLECTOR, #3
13. COLLECTOR, #4
14. BASE, #4
15. EMITTER, #4
16. COLLECTOR, #4</p> | <p>STYLE 4:</p> <p>PIN 1. COLLECTOR, DYE #1
2. COLLECTOR, #1
3. COLLECTOR, #2
4. COLLECTOR, #2
5. COLLECTOR, #3
6. COLLECTOR, #3
7. COLLECTOR, #4
8. COLLECTOR, #4
9. BASE, #4
10. EMITTER, #4
11. BASE, #3
12. EMITTER, #3
13. BASE, #2
14. EMITTER, #2
15. BASE, #1
16. EMITTER, #1</p> |
| <p>STYLE 5:</p> <p>PIN 1. DRAIN, DYE #1
2. DRAIN, #1
3. DRAIN, #2
4. DRAIN, #2
5. DRAIN, #3
6. DRAIN, #3
7. DRAIN, #4
8. DRAIN, #4
9. GATE, #4
10. SOURCE, #4
11. GATE, #3
12. SOURCE, #3
13. GATE, #2
14. SOURCE, #2
15. GATE, #1
16. SOURCE, #1</p> | <p>STYLE 6:</p> <p>PIN 1. CATHODE
2. CATHODE
3. CATHODE
4. CATHODE
5. CATHODE
6. CATHODE
7. CATHODE
8. CATHODE
9. ANODE
10. ANODE
11. ANODE
12. ANODE
13. ANODE
14. ANODE
15. ANODE
16. ANODE</p> | <p>STYLE 7:</p> <p>PIN 1. SOURCE N-CH
2. COMMON DRAIN (OUTPUT)
3. COMMON DRAIN (OUTPUT)
4. GATE P-CH
5. COMMON DRAIN (OUTPUT)
6. COMMON DRAIN (OUTPUT)
7. COMMON DRAIN (OUTPUT)
8. SOURCE P-CH
9. SOURCE P-CH
10. COMMON DRAIN (OUTPUT)
11. COMMON DRAIN (OUTPUT)
12. COMMON DRAIN (OUTPUT)
13. GATE N-CH
14. COMMON DRAIN (OUTPUT)
15. COMMON DRAIN (OUTPUT)
16. SOURCE N-CH</p> | |

SOLDERING FOOTPRINT

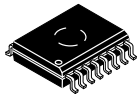


DIMENSIONS: MILLIMETERS

DOCUMENT NUMBER:	98ASB42566B	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	SOIC-16	PAGE 1 OF 1

ON Semiconductor and ON are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

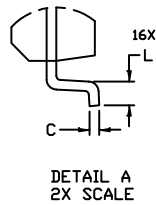
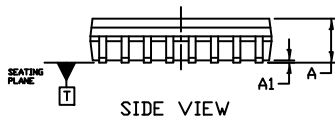
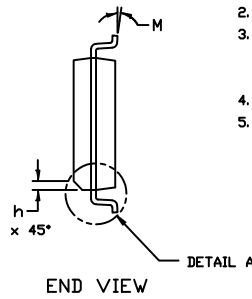
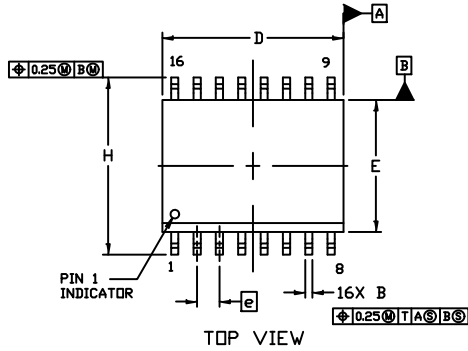
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



1
SCALE 1:1

SOIC-16 WB
CASE 751G
ISSUE E

DATE 08 OCT 2021

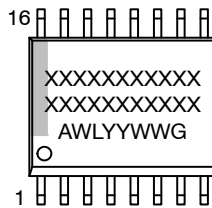


NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION *b* DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF *B* DIMENSION AT MAXIMUM MATERIAL CONDITION.
- DIMENSIONS *D* AND *E* DO NOT INCLUDE MOLD PROTRUSIONS.
- MAXIMUM MOLD PROTRUSION OR FLASH TO BE 0.15 PER SIDE.

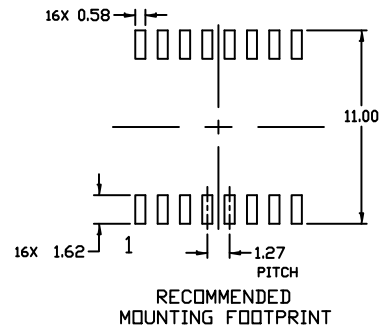
DIM	MILLIMETERS	
	MIN.	MAX.
A	2.35	2.65
A1	0.10	0.25
B	0.35	0.49
C	0.23	0.32
D	10.15	10.45
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.53 REF	
L	0.50	0.90
M	0°	7°

GENERIC MARKING DIAGRAM*



- XXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.



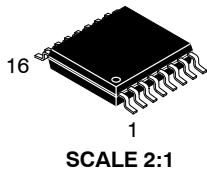
DOCUMENT NUMBER:	98ASB42567B	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	SOIC-16 WB	PAGE 1 OF 1

onsemi and onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

MECHANICAL CASE OUTLINE

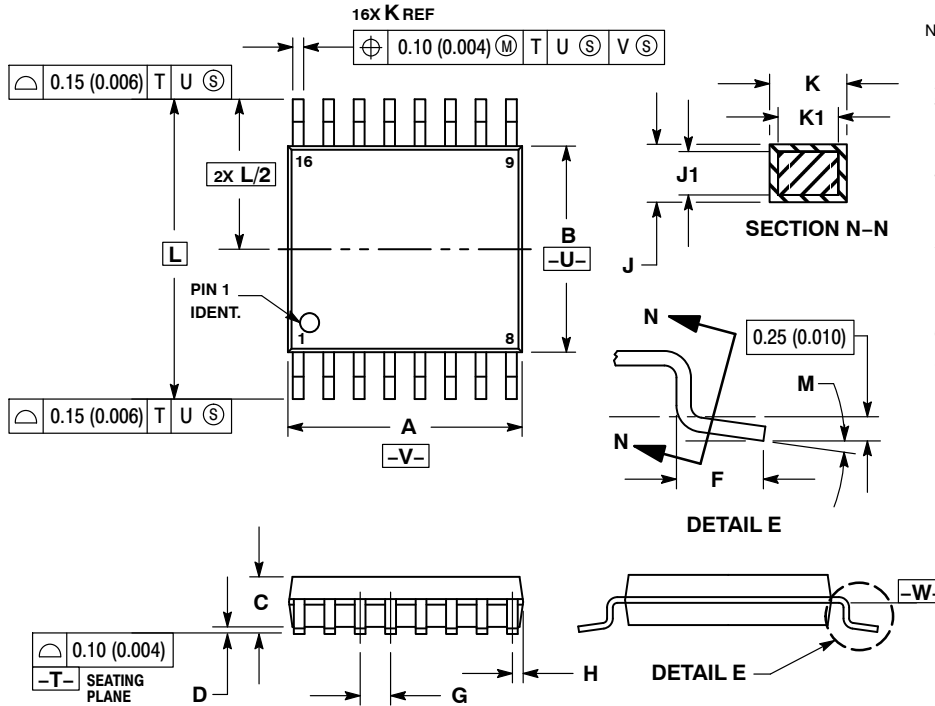
PACKAGE DIMENSIONS

ON Semiconductor®



TSSOP-16
CASE 948F-01
ISSUE B

DATE 19 OCT 2006

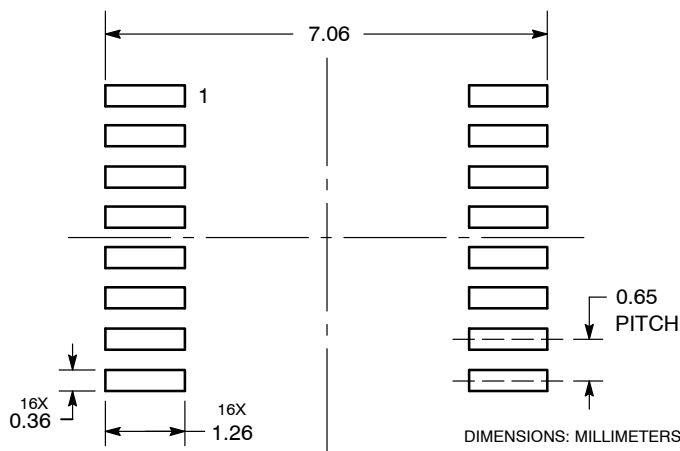


NOTES:

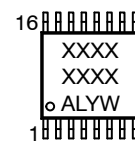
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

SOLDERING FOOTPRINT



GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- G or ■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

DOCUMENT NUMBER:	98ASH70247A	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	TSSOP-16	PAGE 1 OF 1

ON Semiconductor and ON are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT

North American Technical Support:
Voice Mail: 1 800-282-9855 Toll Free USA/Canada
Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative